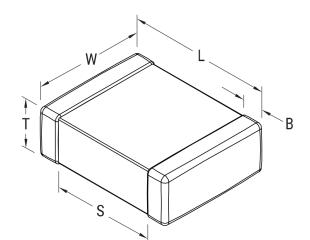


C0805X563J2RAC7210

SMD Comm X7R Flex, Ceramic, 0.056 uF, 5%, 200 VDC, X7R, SMD, MLCC, FT-CAP, Temperature Stable, 0805



Click here for the 3D model.

Dimensions	
Chip Size	0805
L	2mm +/-0.3mm
W	1.25mm +/-0.3mm
Т	1.25mm +/-0.15mm
S	0.75mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

General Information	
Series	SMD Comm X7R Flex
Style	SMD Chip
Description	SMD, MLCC, FT-CAP, Temperature Stable
Features	FT-CAP, Temperature Stable
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Component Weight	21 mg
Shelf Life	78 Weeks
MSL	1

Specifications	
Capacitance	0.056 uF
Measurement Condition	1 kHz 1.0Vrms
Capacitance Tolerance	5%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+125°C
Temperature Coefficient	X7R
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	15%, 1kHz 1.0Vrms
Dissipation Factor	2.5% 1 kHz 1.0Vrms
Aging Rate	3% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	17.8571 GOhms

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